

# MOSFET– Specified, Dual P-Channel, POWERTRENCH®

## 2.5 V

### FDC6306P

#### General Description

These P-Channel 2.5 V specified MOSFETs are produced using onsemi’s advanced PowerTrench process that has been especially tailored to minimize on-state resistance and yet maintain low gate charge for superior switching performance.

These devices have been designed to offer exceptional power dissipation in a very small footprint for applications where the bigger more expensive SO-8 and TSSOP-8 packages are impractical.

#### Features

- -1.9 A, -20 V.  $R_{DS(ON)} = 0.170 \Omega @ V_{GS} = -4.5 V$   
 $R_{DS(ON)} = 0.250 \Omega @ V_{GS} = -2.5 V$
- Low Gate Charge (3 nC Typical)
- Fast Switching Speed
- High Performance Trench Technology for Extremely Low  $R_{DS(ON)}$
- SuperSOT™ -6 Package: Small Footprint (72% Smaller than Standard SO-8); Low Profile (1 mm Thick).
- These Devices are Pb-Free and are RoHS Compliant

#### Applications

- Load Switch
- Battery Protection
- Power Management

#### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ unless otherwise noted)

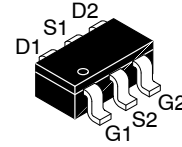
Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-Source Voltage	-20	V
$V_{GSS}$	Gate-Source Voltage	$\pm 8$	V
$I_D$	Drain Current – Continuous (Note 1a) – Pulsed	-1.9 -5	A
$P_D$	Power Dissipation for Single Operation (Note 1a) (Note 1b) (Note 1c)	0.96 0.9 0.7	W
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

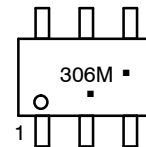
Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	130	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	60	$^\circ C/W$

$V_{DSS}$	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
-20 V	0.170 $\Omega @ -4.5 V$	-1.9 A
	0.250 $\Omega @ -2.5 V$	



TSOT23 6-Lead  
SUPERSOT-6  
CASE 419BL

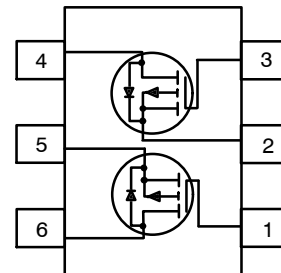
#### MARKING DIAGRAM



- 306 = Specific Device Code  
M = Assembly Operation Month  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

#### PIN CONNECTIONS



#### ORDERING INFORMATION

Device	Package	Shipping†
FDC6306P	TSOT23 6-Lead (Pb-Free, Halide Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

# FDC6306P

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-20	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$	-	-18	-	mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -16\text{ V}, V_{GS} = 0\text{ V}$	-	-	-1	$\mu\text{A}$
$I_{GSSF}$	Gate to Source Leakage Current, Forward	$V_{GS} = 8\text{ V}, V_{DS} = 0\text{ V}$	-	-	100	nA
$I_{GSSR}$	Gate to Source Leakage Current, Reverse	$V_{GS} = -8\text{ V}, V_{DS} = 0\text{ V}$	-	-	-100	nA

### ON CHARACTERISTICS (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-0.4	-0.9	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$	-	3	-	mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = -4.5\text{ V}, I_D = -1.9\text{ A}$ $V_{GS} = -4.5\text{ V}, I_D = -1.9\text{ A}$ @ $T_J = 125^\circ\text{C}$ $V_{GS} = -2.5\text{ V}, I_D = -1.7\text{ A}$	-	0.127 0.182 0.194	0.170 0.270 0.250	$\Omega$
$I_{D(on)}$	On-State Drain Current	$V_{GS} = -4.5\text{ V}, V_{DS} = -5\text{ V}$	-5	-	-	A
$g_{FS}$	Forward Transconductance	$V_{DS} = -5\text{ V}, I_D = -1.9\text{ A}$	-	4	-	S

### DYNAMIC CHARACTERISTICS

$C_{iss}$	Input Capacitance	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	-	441	-	pF
$C_{oss}$	Output Capacitance		-	127	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	67	-	pF

### SWITCHING CHARACTERISTICS (Note 2)

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = -10\text{ V}, I_D = -1\text{ A},$ $V_{GS} = -4.5\text{ V}, R_{GEN} = 6\ \Omega$	-	6	12	ns
$t_r$	Turn-On Rise Time		-	9	18	ns
$t_{d(off)}$	Turn-Off Delay Time		-	14	25	ns
$t_f$	Turn-Off Fall Time		-	3	9	ns
$Q_{g(Tot)}$	Total Gate Charge	$V_{DS} = -10\text{ V}, I_D = -1.9\text{ A},$ $V_{GS} = -4.5\text{ V}$	-	3	4.2	nC
$Q_{gs}$	Gate-Source Charge		-	0.7	-	nC
$Q_{gd}$	Gate-Drain Charge		-	0.8	-	nC

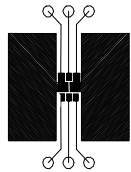
### DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS

$I_S$	Maximum Continuous Drain-Source Diode Forward Current	-	-	-0.8	A	
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -0.8\text{ A}$ (Note 2)	-	-0.8	-1.2	V

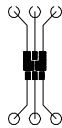
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### NOTES:

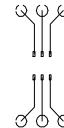
- $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design. Both devices are assumed to be operating and sharing the dissipated heat energy equally.



a.  $130^\circ\text{C/W}$  when mounted on a  $0.125\text{ in}^2$  pad of 2 oz. copper.



b.  $140^\circ\text{C/W}$  when mounted on a  $0.005\text{ in}^2$  pad of 2 oz. copper.



c.  $180^\circ\text{C/W}$  when mounted on a  $0.0015\text{ in}^2$  pad of 2 oz. copper.

Scale 1:1 on letter size paper

- Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$

TYPICAL CHARACTERISTICS

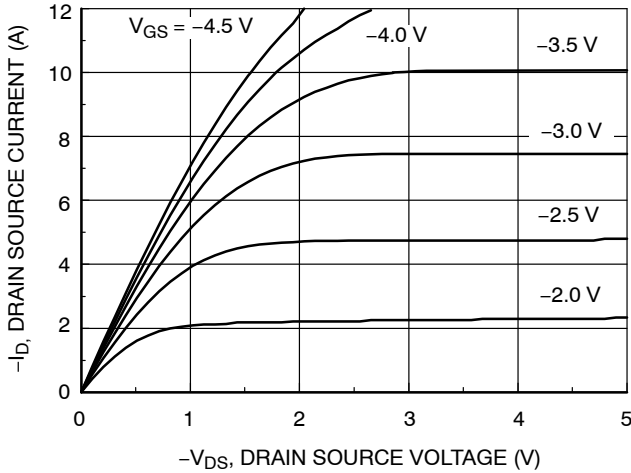


Figure 1. On-Region Characteristics

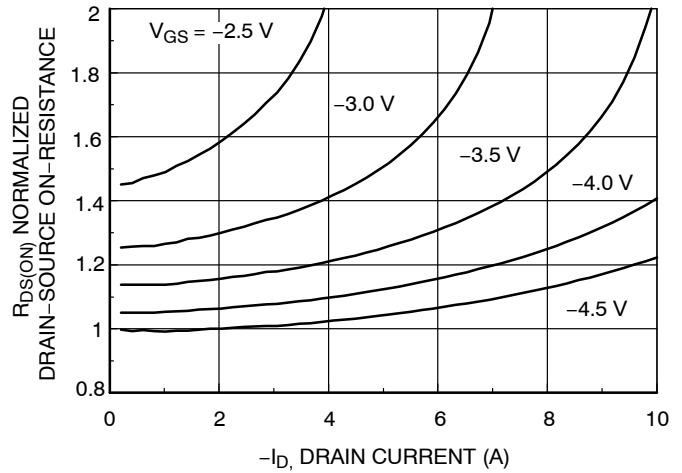


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

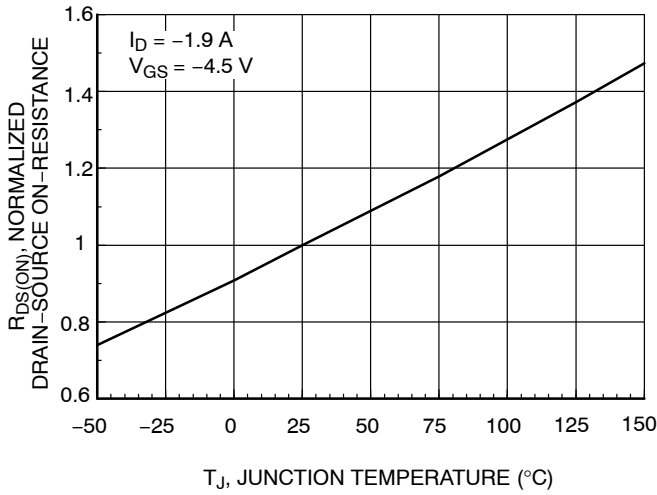


Figure 3. On-Resistance Variation with Temperature

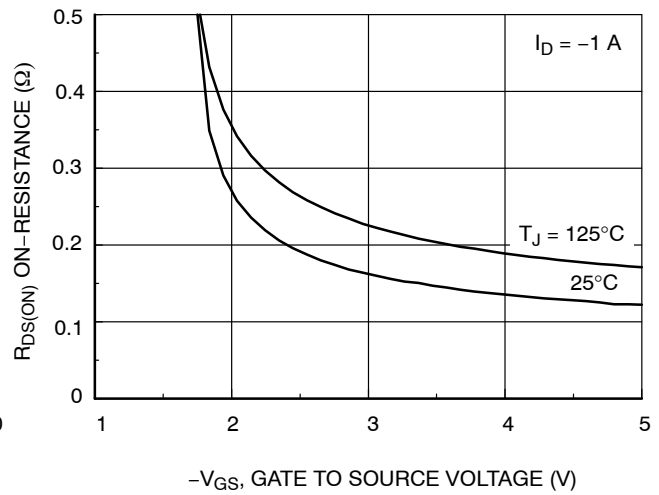


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

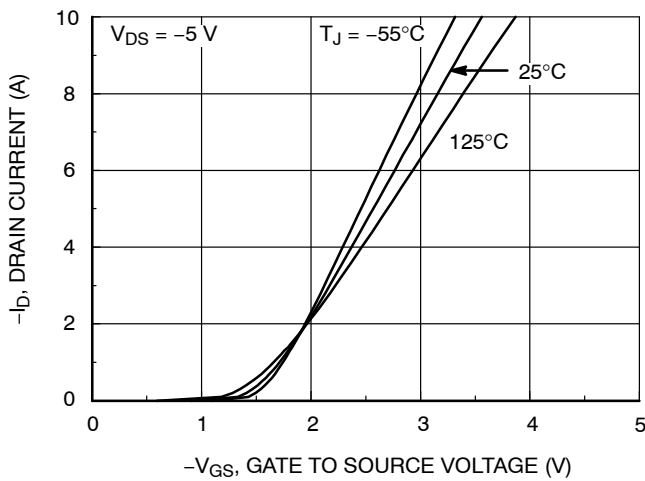


Figure 5. Transfer Characteristics

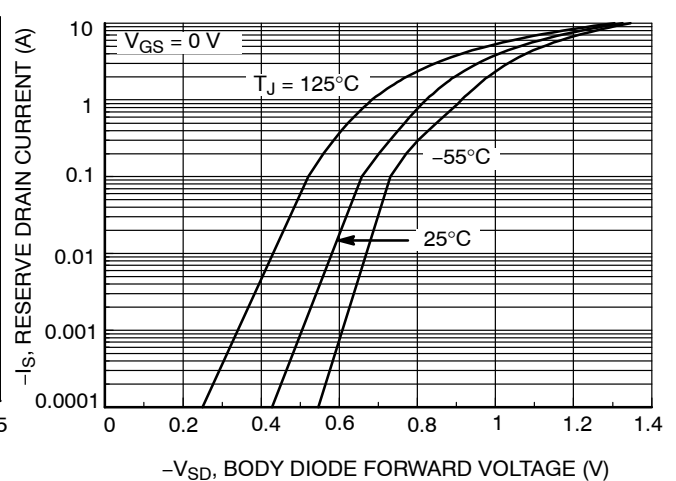
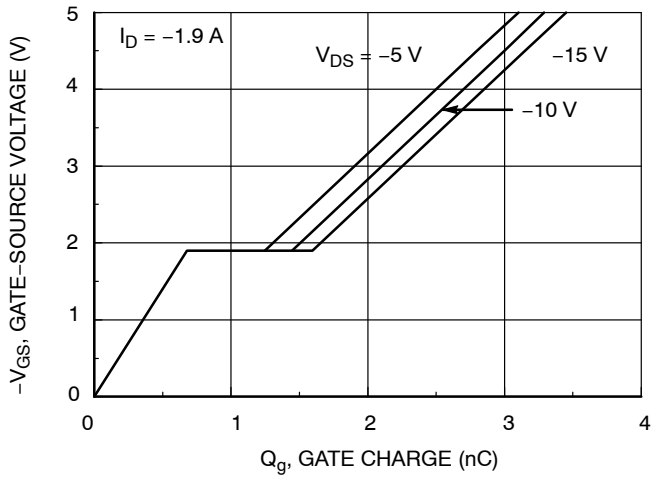
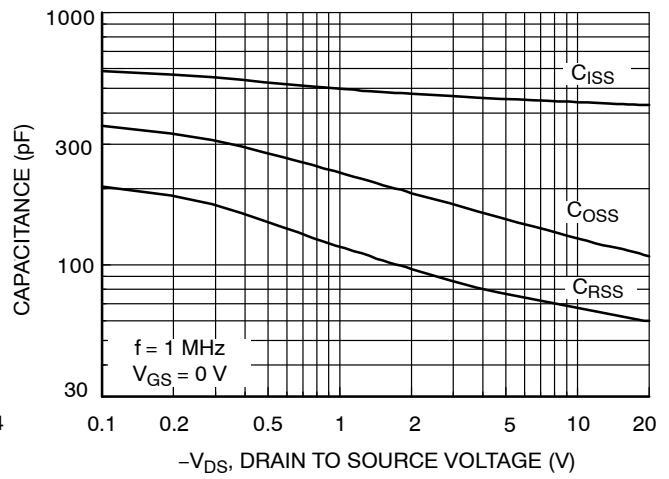


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

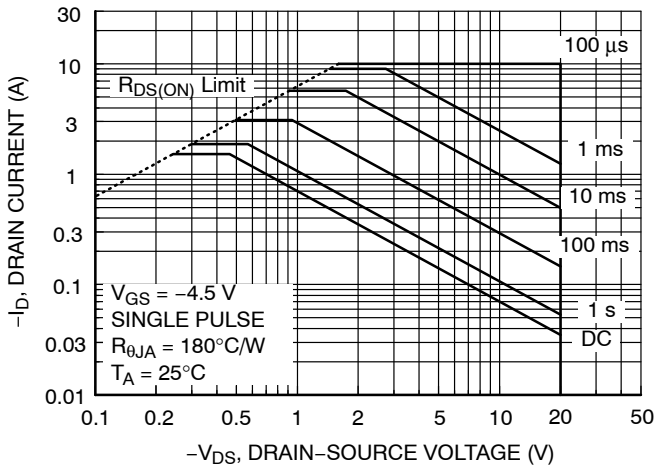
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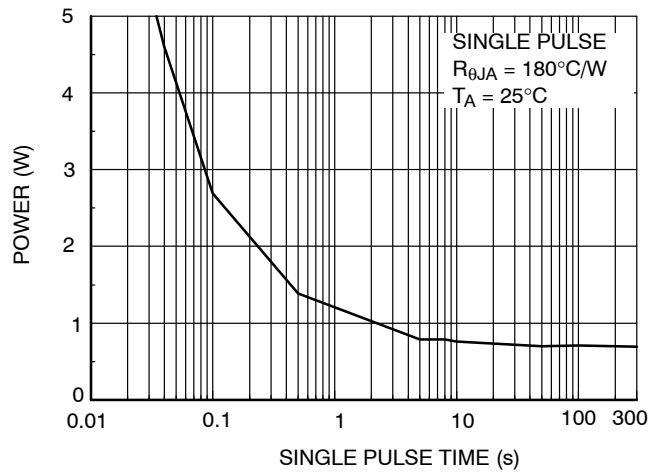
**Figure 7. Gate Charge Characteristics**



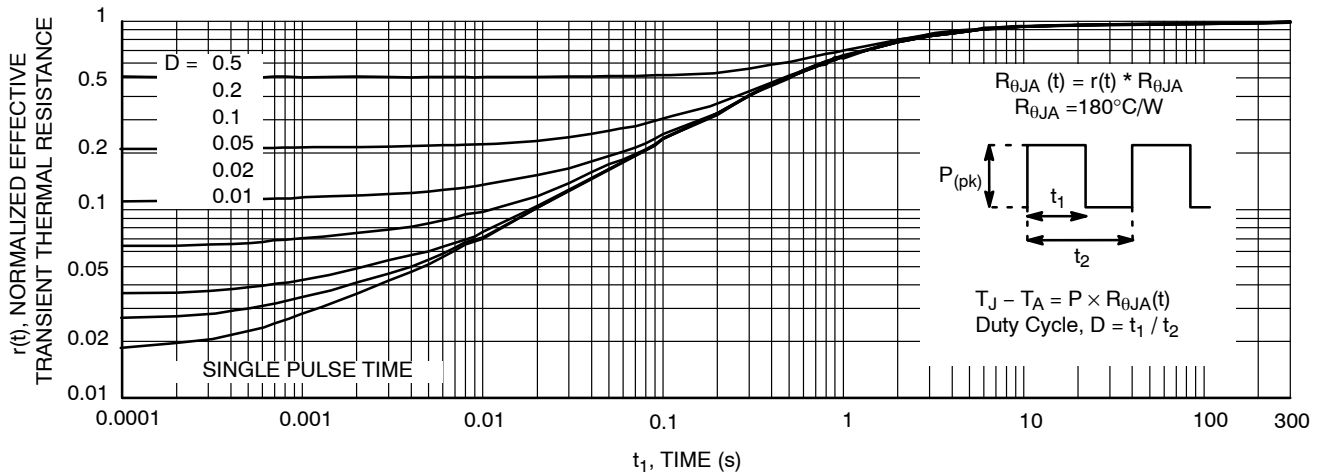
**Figure 8. Capacitance Characteristics**



**Figure 9. Maximum Safe Operating Area**



**Figure 10. Single Pulse Maximum Power Dissipation**



**Figure 11. Transient Thermal Response Curve**

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®



1  
SCALE 2:1

### TSOT23 6-Lead CASE 419BL ISSUE A

DATE 31 AUG 2020



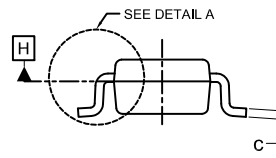
TOP VIEW



FRONT VIEW

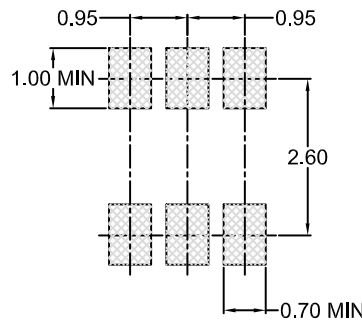


DETAIL A



SIDE VIEW

SYMM  
⌀



LAND PATTERN  
RECOMMENDATION

\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.25MM PER END. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
4. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.00	0.05	0.10
A2	0.70	0.85	1.00
A3	0.25 BSC		
b	0.25	0.38	0.50
c	0.10	0.18	0.26
D	2.80	2.95	3.10
d	0.30 REF		
E	2.50	2.75	3.00
E1	1.30	1.50	1.70
e	0.95 BSC		
e1	1.90 BSC		
L1	0.60 REF		
L2	0.20	0.40	0.60
⌀	0°	--	10°

#### GENERIC MARKING DIAGRAM\*



XXX = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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